



Semicon China: Booth 2401

ERS extends CLIC Partnership to Mainland China

MUNICH, March 9, 2016 – ERS electronic GmbH, the innovation leader in the market of thermal test solutions for semiconductor production, is extending its partnership with Taiwan-based Chain Logic International Corp. (CLIC) to the market of mainland China. With this move, the proven and fruitful collaboration with CLIC on the Taiwanese market finds its logical extension. Within the scope of the partnership, CLIC will represent ERS at the upcoming Semicon China trade fair (March 15 – 17).

At the fair, ERS plans to address the market segment for chuck systems. In this context, the company also will showcase a leading-edge chuck system at the CLIC booth (booth 2401). A second focus topic will be ERS' latest achievements in the area of embedded wafer level BGA (eWLB) product testing.

“CLIC is a well-established market leader in the field of semiconductor testing equipment”, explains Klemens Reiting, Managing Director of ERS electronic GmbH. “With its extensive experience, its sound technological expertise in sales and service, and its excellent reputation, CLIC is a perfect fit for our long-term strategy. CLIC's outstanding quality consciousness aligns with its commitment to sell only high-quality products”.

“ERS ideally complements our portfolio of high-grade semiconductor test solutions,” comments Steven Chan, President of CLIC Corp. “The corporate philosophy of both companies is congruent, fulfilling all prerequisites for a long-term successful partnership.”

Meeting place for one of the world's most dynamic semiconductor industries, Semicon China is an ideal place to launch the strategic collaboration between ERS and CLIC. The event is regarded as China's most important exhibition for the microelectronics industry. It is expected that this year's Semicon, taking place in Shanghai, will attract about 950 exhibitors and more than 50,000 visitors.

About ERS:

ERS electronic GmbH, based in Germering near Munich, has been producing innovative thermal test solutions for the semiconductor industry for 45 years. The company has gained an outstanding reputation in the sector, notably with its fast and accurate thermal chuck systems for test temperatures ranging from -65°C to +500°C for analytical, parameter-related and manufacturing tests. Today, thermal chuck systems developed by ERS in its product families AC3, AirCool®, AirCool® plus and PowerSense® are an integral component in all larger-sized wafer probers right across the chip industry.

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